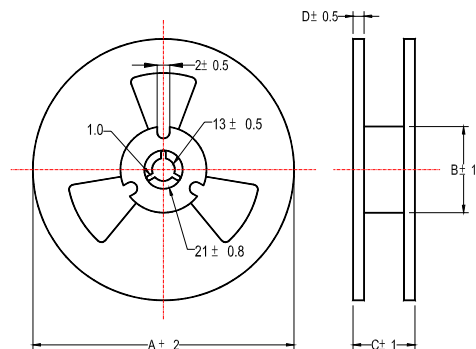


MULTILAYER FERRITE CHIP BEADS

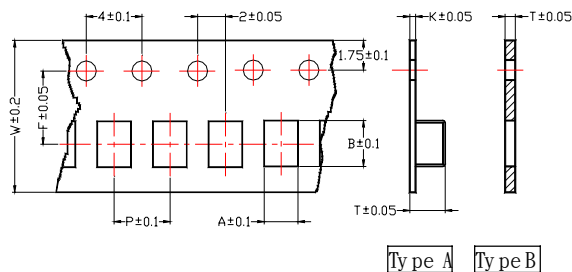


Packaging

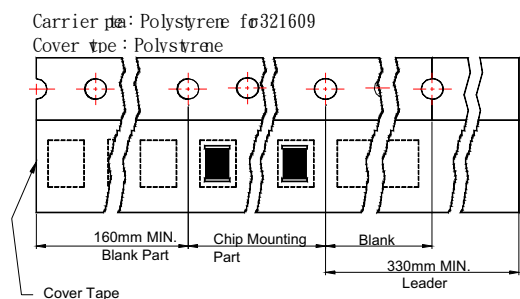
Reel Specifications



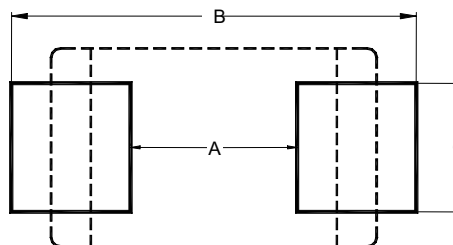
Tape Specifications



Tape Material



Recommended Pattern



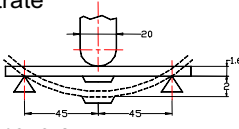

* Don't apply narrower pattern than listed above to CB□□YTYH.
Narrow pattern might cause excessive heat or open circuit.

Dimensions in mm

TYPE	Tape Dimensions								Reel Dimensions				Recommended Pattern			Quantity /Reel
	A	B	T	W	P	F	K	Tape Typ.	A	B	C	D	A	B	C	
CB02	0.62	1.15	0.7	8.0	2.0	3.5	-	B	178	60	10	2	0.4	1.2 ~ 1.4	0.4	10000
CB03	1.05	1.80	0.95	8.0	4.0	3.5	-	B	178	60	10	2	0.8	2.4 ~ 3.4	0.6	4000
CB05	1.42	2.30	1.05	8.0	4.0	3.5	0.2	A	178	60	10	2	1.2	3.0 ~ 4.0	1.0	4000
CB04	1.88	3.50	1.27	8.0	4.0	3.5	0.2	A	178	60	10	2	2.0	4.2 ~ 5.2	1.2	3000
CB06	1.88	3.64	1.90	8.0	4.0	3.5	0.2	A	178	60	10	2	2.0	4.2 ~ 5.2	1.2	2000
CB10	2.77	3.42	1.65	8.0	4.0	3.5	0.2	A	178	60	10	2	2.0	5.5 ~ 6.5	1.8	2500
CB08	1.88	4.95	1.90	12	4.0	5.5	0.3	A	178	60	14	2	3.0	5.5 ~ 6.5	1.2	2000
CB12	3.66	4.95	1.85	12	8.0	5.5	0.3	A	178	60	14	2	3.0	5.5 ~ 6.5	2.4	1000



Environmental Characteristics

Item	Specification	Test Method															
1	Flexure Strength Appearance: No damage Z change: within±20% RDC: within specification	Test device shall be soldered on the substrate Substrate Dimension: 100x40x1.6mm Deflection: 2.0mm Keeping Time: 30sec *For 100505, substrate dimension is 100x40x0.8mm 															
2	Vibration	Test device shall be soldered on the substrate Oscillation Frequency: 10 to 55 to 10Hz for 1min Amplitude: 1.5mm Time: 2hrs for each axis (X, Y & Z), total 6hrs															
3	Resistance to Soldering Heat Appearance: No damage	Pre-heating: 150°C, 1min Solder Composition: Sn/Pb = 63/37 Solder Temperature: 260±5°C Immersion Time: 10±1sec															
4	Solderability The electrodes shall be at least 90% covered with new solder coating	Pre-heating: 150°C, 1min Solder Composition: Sn/Pb = 63/37 Solder Temperature: 230±5°C Immersion Time: 4±1sec															
	Terminal Strength Test 100505 series : ≥ 0.2 kg 160808 series : ≥ 0.5 kg 201209 series : ≥ 1.0 kg other series : ≥ 2.0 kg	Test device shall be soldered on the substrate 															
	Temperature Cycle Appearance: No damage Z change: within±20% RDC: within specification	One cycle: - <table border="1" data-bbox="874 1057 1337 1258"> <thead> <tr> <th>Step</th> <th>Temperature (°C)</th> <th>Time (min)</th> </tr> </thead> <tbody> <tr> <td>1</td> <td>-55±3</td> <td>30</td> </tr> <tr> <td>2</td> <td>25±2</td> <td>3</td> </tr> <tr> <td>3</td> <td>125±3</td> <td>30</td> </tr> <tr> <td>4</td> <td>25±2</td> <td>3</td> </tr> </tbody> </table> Total: 100cycles Measured after exposure in the room condition for 24hrs	Step	Temperature (°C)	Time (min)	1	-55±3	30	2	25±2	3	3	125±3	30	4	25±2	3
Step	Temperature (°C)	Time (min)															
1	-55±3	30															
2	25±2	3															
3	125±3	30															
4	25±2	3															
	Humidity Resistance	Temperature: 40±2°C Relative Humidity: 90 ~ 95% Time: 1000hrs Measured after exposure in the room condition for 24hrs															
8	High Temperature Resistance	Temperature: 125±3°C Relative Humidity: 0% Applied Current: Rated Current Time: 1000hrs Measured after exposure in the room condition for 24hrs															
9	Low Temperature Resistance	Temperature: -55±3°C Relative Humidity: 0% Time: 1000hrs Measured after exposure in the room condition for 24hrs															